

Joint Session (Area 4&12)

A-5: Nonvolatile Memory and Storage Devices

9:30-11:10 Meeting Room 1

Session Chair: T. Kondo (Toshiba Corp.)

H. Sato (Tohoku Univ.)

9:30 A-5-01 (Invited)

Accumulative Magnetic Switching of Ultrahigh-Density Recording Media by Circularly Polarized Light

°Y. K. Takahashi¹, R. Medapalli², S. Kasai¹, J. Wang¹, K. Ishioka¹, S. H. Wee³, O. Hellwig⁴, K. Hono¹, E. E. Fullerton², ¹NIMS (Japan), ²UCSD (USA), ³HGST (USA), ⁴Institut für Ionenstrahlphysik und Materialforschung (Germany)

10:00 A-5-02

Switching Mechanism Design for High-speed Voltage-Control Spintronics Memory (VoCSM) Considering the Operation Window

°K. Koi¹, H. Yoda¹, N. Shimomura¹, T. Inokuchi¹, Y. Kato¹, B. Altansargai¹, S. Shirotori¹, Y. Kamiguchi¹, K. Ikegami¹, S. Oikawa¹, H. Sugiyama¹, M. Shimizu¹, M. Ishikawa¹, T. Ajay¹, Y. Ohsawa¹, Y. Saito¹, A. Kurobe¹, ¹Toshiba Corp. (Japan)

10:20 A-5-03

Cross Point Type 1T-1MTJ STT-MRAM Cell with 60 nm Multi-pillar Vertical Body Channel MOSFET under 55 nm p-MTJ and Its Beyond for High Density STT-MRAM

°T. Sasaki^{1,2,3}, T. Endoh^{1,2,3}, ¹Tohoku Univ. (Japan), ²ACCEL, JST (Japan), ³OPERA, JST (Japan)

10:40 A-5-04 (Invited)

Key advanced technology for eMRAM development

°J. Lee¹, H. Jung¹, K. Lee¹, Y. Song¹, G. -H. Koh¹, G. -T. Jeong, ¹Samsung Electronics Co., Ltd. (Korea)

11:10-11:15

Coffee Break

Friday, September 22

A-6: Novel Memory

11:15-12:15 Meeting Room 1

Session Chair: T. Ono (Kyoto Univ.)

K. Kinoshita (Tokyo Univ. of Science)

11:15 A-6-01

Voltage-Control Spintronics Memory (VoCSM) having a potential of high write-efficiency

^oM. Shimizu¹, H. Yoda¹, S. Shirotori¹, N. Shimomura¹, Y. Ohsawa¹, T. Inokuchi¹, K. Koui¹, Y. Kato¹, S. Oikawa¹, H. Sugiyama¹, A. Buyandalai¹, M. Ishikawa¹, K. Ikegami¹, Y. Kamiguchi¹, Y. Saito¹, A. Kurobe¹, ¹Toshiba Corp. (Japan)

11:35 A-6-02

Sub 1 V 60 nm Vertical Body Channel MOSFET Based 6T SRAM Array with Wide Noise Margin and Excellent Power Delay Product

^oR. Ogasawara^{1,2,3}, T. Endoh^{1,2,3}, ¹Tohoku Univ. (Japan),
²ACCEL, JST (Japan), ³OPERA, JST (Japan)

11:55 A-6-03

In-situ Observation of Cu Residuals in Resistance Switching Failure of MoO_x/Al₂O₃ CBRAM

^oM. Arita¹, R. Ishikawa¹, S. Hirata¹, A. Turumaki-Fukuchi¹, Y. Takahashi¹, ¹Hokkaido Univ. (Japan)

12:15-13:40

Lunch

04: Advanced Memory Technology

A-7: ReRAM Applications

13:40-15:00 Meeting Room 1

Session Chair: Y. Jono (Micron Memory Japan Inc.)

Y. Hikosaka (Fujitsu Semiconductor Ltd.)

13:40 A-7-01

The Experimental Observations of a New Dielectric-fuse Breakdown in a Bilayer-RRAM to Realize the OTP Functionality

^oE. R. Hsieh¹, H. W. Cheng¹, Z. H. Huang¹, C. H. Chuang¹, C. H. Chen¹, S. Chung¹, ¹National Chiao Tung Univ. (Taiwan)

Friday, September 22

14:00 A-7-02

A Novel Ternary Content Addressable Memory Design Based on RRAM with High Intensity and Low Search Energy

°R. Han¹, W. Shen¹, P. Huang¹, Z. Zhou¹, L. Liu¹, X. Liu¹, J. Kang¹, ¹Peking Univ. (China)

14:20 A-7-03

Error Free Physically Unclonable Function (PUF) with Programmed ReRAM using Reliable Resistance States by Novel ID-Generation Method

°P. H. Tseng¹, ¹Macronix International Co., Ltd. (Taiwan)

14:40 A-7-04

Highly Reliable Logic-Compatible MTP Memory for Automotive Applications

°C. Y. Lo¹, S. C. Wang¹, ¹eMemory Technology Inc. (Taiwan)

15:00-15:10

Coffee Break

A-8: PCRAM

15:10-16:55 Meeting Room 1

Session Chair: S. Jeon (Korea Univ.)

Y. Hikosaka (Fujitsu Semiconductor Ltd.)

15:10 A-8-01 (Invited)

Transition Metal-Ge-Te Chalcogenides for PCRAM Material

°Y. Sutou¹, S. Shindo¹, S. Hatayama¹, Y. Saito², J. Koike¹, ¹Tohoku Univ. (Japan), ²AIST (Japan)

15:40 A-8-02

Origin of the difference between high resistive and low resistive structures for interfacial phase change memories based on GeTe/Sb₂Te₃ superlattice

°H. Shirakawa¹, M. Araidai¹, K. Shiraishi¹, ¹Nagoya Univ. (Japan)

16:00 A-8-03

Thermal Stability and Switching Performance of iPCM at Elevated Temperature

Friday, September 22

°K. V. Mitrofanov¹, Y. Saito¹, N. Miyata¹, P. Fons¹, A. V. Kolobov¹, J. Tominaga¹, ¹AIST (Japan)

16:20 A-8-04

Continuous Multilevel Compact Model of Subthreshold Conduction and Threshold Switching in Phase-Change Memory

°C. Pigot^{1,2,3}, F. Gilibert¹, M. Reyboz², M. Bocquet³, P. Zuliani⁴, J. -M. Portal³, ¹STMicroelectronics, Crolles (France), ²CEA-Leti (France), ³IM2NP, Aix-Marseille Univ. (France), ⁴STMicroelectronics, Agrate (Italy)

16:40 A-8-05 (Late News)

Programming Current Reduction in GeS₂+Sb₂Te₃ Based Phase-Change Memory

°J. Kluge^{1,2,3}, A. Verdy², G. Navarro², S. Blonkowski¹, V. Sousa², P. Kowalczyk², M. Bernard², N. Bernier², G. Bourgeois², N. Castellani², P. Noé², E. Nowak², L. Perniola², ¹STMicroelectronics (France), ²CEA-Leti (France), ³IMEP-LAHC (France)

Joint Session (Area 10&15)

B-5: Quantum Dot/Organic Solar Cells

9:30-10:45 Meeting Room 2

Session Chair: M. Ikegami (Toin Univ. of Yokohama)
T. Kaji (Tokyo Univ. of Agri. & Tech.)

9:30 B-5-01 (Invited)

Solution-processed solar cells with nanostructured hybrid materials

°T. Kubo¹, H. Wang¹, H. Segawa¹, ¹Univ. of Tokyo (Japan)

10:00 B-5-02

0-dimensional Carbon Dot as Efficient Cathode Interfacial Layers for Organic Photovoltaics Providing Power Conversion Efficiencies up to 9.5%

°J. -C. Kao¹, C. -P. Chen¹, ¹Ming Chi Univ. of Tech. (Taiwan)

Friday, September 22

10:15 B-5-03

The research on the principle of high V_{oc} in Schottky type organic photovoltaic cells with low concentrated donors
°F. Enokido¹, M. Yogo¹, M. Katayama¹, T. Kaji¹, ¹Tokyo Univ. of Agri. & Tech. (Japan)

10:30 B-5-04

Highly stable organic-inorganic perovskite solar cells
C. Qin^{1,2}, °T. Matsushima^{1,2}, T. Fujihara³, C. Adachi^{1,2},
¹Kyushu Univ. (Japan), ²JST, ERATO (Japan), ³ISIT (Japan)

10:45-11:15

Coffee Break

15: Photovoltaic Materials and Devices

B-6: Perovskite Solar Cells

11:15-12:30 Meeting Room 2

Session Chair: M. Chikamatsu (AIST)

T. Taima (Kanazawa Univ.)

11:15 B-6-01

The Influence of O₂ Plasma Treatment to NiO_x Layer for Perovskite Solar Cells

°Y. Nishihara^{1,2}, M. Chikamatsu¹, S. Kazaoui¹, T. Miyadera¹, Y. Yoshida^{1,2}, ¹AIST (Japan), ²Univ. of Tsukuba (Japan)

11:30 B-6-02

Low Temperature Processed Atomically Thin Perovskite Oxide as Electron Transporting Layer in Perovskite Solar Cells

°Y. -H. Tsai¹, S. -S. Li¹, K. Tsukagoshi², T. Sasaki², M. Osada², C. -W. Chen¹, ¹National Taiwan Univ. (Taiwan), ²NIMS (Japan)

11:45 B-6-03

High Mobility Fullerene Derivative as Interface Engineering of Amorphous Compact-TiO_x for Planar Perovskite Solar Cells

°M. Shahiduzzaman¹, M. Karakawa¹, K. Yamamoto¹, K. Yonezawa¹, T. Kuwabara¹, K. Takahashi¹, T. Taima¹,

Friday, September 22

¹*Kanazawa Univ. (Japan)*

12:00 B-6-04

Semitransparent Perovskite Solar Cells With Thin Metal Electrodes

°*H. Chintam*^{1,2}, *K. M. Boopathi*¹, *C. S. Lai*², *C. W. Chu*¹,
¹*Academia Sinica (Taiwan)*, ²*Chang Gung Univ. (Taiwan)*

12:15 B-6-05

Simple Structured Polyetheramines, as Electron Transporting Modified Layers for Efficient Organic Photovoltaics

°*Y. -Y. Tsai*¹, *B. -H. Jiang*¹, *C. -P. Chen*¹, ¹*Ming Chi Univ. of Tech. (Taiwan)*

07: Photonic Devices and Related Technologies

C-5: Silicon Photonics I

9:30-10:45 Meeting Room 3

Session Chair: *M. Shirao* (Mitsubishi Electric Corp.)
S. Sekiguchi (Fujitsu Labs.)

9:30 C-5-01 (Invited)

Integration of Photonics with Digital Processing Units

°*L. Alloatti*¹, ¹*ETH Zürich (Switzerland)*

10:00 C-5-02

High-Performance Surface Illumination-type Ge Photodetector for Optical Interconnection on 300mm-diameter of SOI substrate

°*J. Fujikata*¹, *K. Kinoshita*¹, *S. Takahashi*¹, *T. Horikawa*^{1,2},
*M. Noguchi*¹, *K. Takemura*¹, *D. Okamoto*¹, *Y. Suzuki*¹, *M. Kurihara*¹,
*Y. Hagihara*¹, *T. Nakamura*¹, *K. Kurata*¹, *T. Mogami*¹, ¹*PETRA (Japan)*, ²*AIST (Japan)*

10:15 C-5-03

O-Band CWDM Echelle Grating Demultiplexers on SiNOI Exhibiting Quasi-Absolute Thermal Insensitiveness

°*C. Sciancalepore*¹, *Q. Wilmart*¹, *D. Robin-Brosse*¹, *L. Adelmini*¹,
*S. Malhouitre*¹, *S. Olivier*¹, ¹*CEA-Leti (France)*

Friday, September 22

10:30 C-5-04

CMOS Compatible 200mm Silicon Photonic Platform
Suitable For High Bandwidth Applications

°*B. Szlag¹, B. Charbonnier¹, S. Brision¹, B. Karakus¹, D. Fowler¹, O. Lemonnier¹, J. -M. Hartmann¹, P. Brianceau¹, D. Marris-Morini², E. Cassan², L. Vivien², S. Menezo¹, C. Kopp¹, ¹CEA-Leti (France), ²C2N-Univ. Paris Sud (France)*

10:45-11:15

Coffee Break

09: Physics and Applications of Novel Functional Devices and Materials

C-6: Quantum Transport

11:15-12:30 Meeting Room 3

Session Chair: R. Moriya (Univ. of Tokyo)
T. Kodera (Tokyo Tech)

11:15 C-6-01 (Invited)

1D van der Waals Materials in 2D Form

°*P. Ye¹, ¹Purdue Univ. (USA)*

11:45 C-6-02

Interplay between Kondo effect and superconductivity in a carbon nanotube quantum dot

°*T. Hata¹, M. Ferrier², S. Lee¹, T. Arakawa¹, R. Delagrangé², R. Deblock², H. Bouchiat², K. Kobayashi¹, ¹Osaka Univ. (Japan), ²Univ. Paris Sud (France)*

12:00 C-6-03

Dissipative Landau-Zener transition in capacitance measurement on a double quantum dot

°*T. Ota¹, K. Hitachi¹, K. Muraki¹, T. Fujisawa², ¹NTT Basic Res. Labs. (Japan), ²Tokyo Tech (Japan)*

12:15 C-6-04 (Late News)

Micro Channel Based Heat Sink with Integrated Thin-Film Temperature Sensors

°*J. Wang¹, T. Wang¹, J. He¹, Y. Yang¹, Y. Li¹, H. Jiao¹, C. Wu¹, W. Luo¹, Y. Shuai¹, W. Zhang¹, ¹Univ. of Electronic Sci. and Tech. of China (China)*

12:30-13:40

Lunch

C-7: Quantum Optoelectronics

13:40-14:55 Meeting Room 3

Session Chair: T. Miyazawa (Fujitsu Labs. Ltd.)
T. Ota (NTT Basic Res. Labs.)

13:40 C-7-01

Telecom-Wavelength Quantum Relay using a
Semiconductor Entangled Light Source

J. Huwer¹, M. Felle^{1,2}, ^oM. Stevenson¹, J. Skiba-Szymanska¹, M. Ward¹, I. Farrer², R. Penty², D. Ritchie², A. Shields¹, ¹Toshiba Research Europe Ltd. (UK), ²Univ. of Cambridge (UK)

13:55 C-7-02

Generation and Detection of Edge Magnetoplasmons in a
Quantum Hall Edge Channel Using a Photoconductive
Switch

^oC. Lin¹, K. Morita¹, K. Muraki², T. Fujisawa¹, ¹Tokyo Tech (Japan), ²NTT Basic Res. Labs. (Japan)

14:10 C-7-03

Electrically Tunable Coupling of a Ge/Si Core/Shell
Nanowire Double Quantum to a Superconducting
Transmission Line Cavity

^oR. Wang¹, R. S. Deacon^{1,2}, J. Yao³, C. M. Lieber³, K. Ishibashi^{1,2}, ¹RIKEN (Japan), ²CEMS, RIKEN (Japan), ³Harvard Univ. (USA)

14:25 C-7-04

Terahertz response in the quantum Hall effect regime of a
quantum-well based charge sensitive phototransistor

D. Nakagawa¹, K. Takizawa¹, ^oK. Ikushima¹, S. Kim², M. Patrashin³, I. Hosako³, S. Komiyama², ¹Tokyo Univ. of Agri. & Tech. (Japan), ²Univ. of Tokyo (Japan), ³NICT (Japan)

14:40 C-7-05

Acoustic characteristics of a surface-acoustic-wave
resonator made of two Bragg reflectors with periodic
metallization of GaAs

Friday, September 22

°R. Takasu¹, Y. Sato¹, T. Fujisawa¹, ¹Tokyo Tech (Japan)

03: CMOS Devices / Device Physics

E-5: Steep Slope Transistor and Device Physics

9:30-10:50 Tachibana Conference Room

Session Chair: K. Maekawa (Renesas Electronics Corp.)

R. Huang (Peking Univ.)

9:30 E-5-01 (Invited)

Improvement of Device and Circuit Performance of Si-based Tunnel Field-Effect Transistors by Utilizing Isoelectronic Trap Technology

°T. Mori¹, H. Asai¹, T. Matsukawa¹, ¹AIST (Japan)

10:00 E-5-02

Investigation of Thermal Effects on FinFETs in the Quasi-Ballistic Regime

°L. Yin¹, L. Shen¹, S. Y. Di¹, G. Du¹, X. Y. Liu¹, ¹Peking Univ. (China)

10:20 E-5-03 (Late News)

Optimizing MOS-Gated Thyristor using Voltage-based Equivalent Circuit Model for Designing Steep Subthreshold Slope PN-Body Tied SOI FET

°D. Ueda¹, K. Takeuchi¹, M. Kobayashi¹, T. Hiramoto¹, ¹Univ. of Tokyo (Japan)

10:35 E-5-04 (Late News)

Lowering Minimum Operation Voltage (V_{\min}) in SRAM Array by Post-Fabrication Self-Improvement of Cell Stability by Multiple Stress Application

°T. Mizutani¹, K. Takeuchi¹, T. Saraya¹, M. Kobayashi¹, T. Hiramoto¹, ¹Univ. of Tokyo (Japan)

10:50-11:15

Coffee Break

E-6: 3D Technology

11:15-12:25 Tachibana Conference Room

Session Chair: K. Sukegawa (Socionext Inc.)

F. L. Yang (Academia Sinica)

11:15 E-6-01 (Invited)

Achieving BEOL Footprint-Efficient and Low Cost Monolithic 3D⁺ IoT Chip Using Low Thermal Budget Laser Technology

°C. -C. Yang¹, T. -Y. Hsieh¹, W. -H. Huang¹, J. -M. Shieh¹, H. -H. Wang¹, C. -H. Shen¹, F. -K. Hsueh¹, W. -K. Yeh¹,
¹National Nano Device Labs. (Taiwan)

11:45 E-6-02

Analysis of Inter-and Intra-Grain Defects in Electrically Characterized Poly-Si Nanowire TFTs by Multicomponent DF Imaging Based on NBD-2DI

°T. Asano¹, R. Takaishi¹, M. Oda¹, K. Sakuma¹, M. Saitoh¹, H. Tanaka¹, ¹Toshiba Corp. (Japan)

12:05 E-6-03

Investigation of the Optimum Stacking Number of Stacked Nanowires for Logic Applications

°W. -C. Huang¹, P. Su¹, ¹National Chiao Tung Univ. (Taiwan)

11: Sensors and Materials for Biology, Chemistry and Medicine

F-5: Nano Devices for Chemical & Biosensing

9:30-10:30 Meeting Room 4

Session Chair: M. Sasaki (Toyota Technological Inst.)
T. Sakata (Univ. of Tokyo)

9:30 F-5-01

The Super-Nernstian pH-sensitivity of CeY_xO_y Sensing Membrane Electrolyte-Insulator-Semiconductor Sensors

T. -M. Pan¹, C. -L. Chan¹, °Y. -H. Huang¹, C. -W. Wang¹,
¹Chang Gung Univ. (Taiwan)

9:45 F-5-02

A Super-Nernstian pH Sensor using WO₃ Nanosheets Sensing Electrode

°C. -Y. Kuo¹, R. -M. Ko¹, H. -H. Tseng¹, S. -J. Wang¹,
¹National Cheng Kung Univ. (Taiwan)

Friday, September 22

10:00 F-5-03

Ag/SiO₂ surface-enhanced Raman scattering substrate detection in plasticizer

°T. -H. Lin¹, M. -P. Lin², W. -F. Su², M. -C. Wu¹, ¹Chang Gung Univ. (Taiwan), ²National Taiwan Univ. (Taiwan)

10:15 F-5-04 (Late News)

From single phase to multiphase: single cell encapsulation in a droplet

°G. Pendharkar¹, D. Mukherjee², C. -M. Chang³, Y. -T. Lu³, S. Chakraborty², C. -H. Liu¹, ¹National Tsing Hua Univ. (Taiwan), ²Indian Inst. of Tech. (India), ³Mackay Memorial Hospital (Taiwan)

10:30-11:15 Coffee Break

Joint Session (Area 10&11)

F-6: Organic and Bio Devices

11:15-12:30 Meeting Room 4

Session Chair: S. Nakajima (Japan Aviation Electronics Ind., Ltd.)
R. Tero (Toyohashi Tech)

11:15 F-6-01 (Invited)

Bioorganic Hybrid Nanomaterials in Optics, Electronics and Sensing

I. Mames¹, J. W. Wood¹, J. P. Pursey¹, L. L. Sargisson¹, °E. Stulz¹, ¹Univ. of Southampton (UK)

11:45 F-6-02

Performance Analysis of Multi-metallic Sensor Chip for the Real-time Quantification of EV 71 Virus with SPR Biosensor

°A. Alom¹, B. A. Prabowo¹, P. Pal¹, M. K. Secario¹, P. -T. Ou¹, J. -J. Liu¹, R. Y. L. Wang^{1,2}, K. C. Liu^{1,2}, ¹Chang Gung Univ. (Taiwan), ²Chang Gung Memorial Hospital (Taiwan)

12:00 F-6-03

Adhesive Conductive Polymer for Wearable Electrocardiogram Monitoring

°D. Yamamoto¹, Y. Yamamoto¹, M. Takada¹, H. Naito¹, T. Arie¹, S. Akita¹, K. Takei¹, ¹Osaka Pref. Univ. (Japan)

Friday, September 22

12:15 F-6-04 (Late News)

Highly efficient deep-blue OLED with a novel carbazole based florescent emitter

°S. Sahoo¹, M. Singh¹, V. Joseph², K. R. J. Thomas², J. H. Jou¹, ¹National Tsing Hua Univ. (Taiwan), ²Indian Inst. of Tech. Roorkee (India)

05: Advanced Circuits and Systems

G-5: Advanced Imager and Characterization

9:30-10:40 Meeting Room 5

Session Chair: R. Kuroda (Tohoku Univ.)

H. Majima (Toshiba Corp.)

9:30 G-5-01 (Invited)

Advanced Stacked CMOS Image Sensor Technology

°Y. Nitta¹, ¹Sony Semiconductor Solutions Corp. (Japan)

10:00 G-5-02

Impact of Drain Current to Appearance Probability and Amplitude of Random Telegraph Noise in Low Noise CMOS Image Sensors

°S. Ichino¹, T. Mawaki¹, A. Teramoto¹, R. Kuroda¹, H. Park¹, T. Maeda¹, S. Wakashima¹, T. Goto¹, T. Suwa¹, S. Sugawa¹, ¹Tohoku Univ. (Japan)

10:20 G-5-03

Analysis of Random Telegraph Noise Behaviors of nMOS and pMOS toward Back Bias Voltage Changing

°T. Mawaki¹, A. Teramoto¹, R. Kuroda¹, S. Ichino¹, S. Sugawa¹, ¹Tohoku Univ. (Japan)

10:40-11:15

Coffee Break

G-6: Advanced Computing and Memories for Smart Data Processing

11:15-12:25 Meeting Room 5

Session Chair: I. Akita (Toyohashi Tech)

K. Johguchi (Shinshu Univ.)

Friday, September 22

11:15 G-6-01 (Invited)

HPP: A Novel Architecture for High Performance Processing

D. Wang¹, °Z. Zhang¹, Z. Liu¹, X. Du¹, S. Xie¹, H. Ma¹, G. Ding¹, W. Ren¹, F. Zhou¹, W. Sun¹, H. Wang¹, ¹Inst. of Automation, Chinese Academy of Sci. (China)

11:45 G-6-02

A 28nm High-*k*/Metal-gate Symmetric 10T 2RW Dual-port SRAM bitcell design

T. Y. Lu¹, C. H. Huang¹, S. S. Chen¹, Y. T. Kuo¹, C. C. Lung¹, O. Cheng¹, Y. Ishii², M. Tanaka², M. Yabuuchi², Y. Sawada², S. Tanaka², °K. Nii², ¹United Microelectronics Corp. (Taiwan), ²Renesas Electronics Corp. (Japan)

12:05 G-6-03

Fully Digital Ternary Content Addressable Memory using Ratio-less SRAM Cells and Hierarchical-AND Matching Comparator for Ultra-low-voltage Operation

°D. Nishikata¹, M. A. Bin Mohd Ali¹, K. Hosoda¹, H. Matsumoto¹, K. Nakamura¹, ¹Kyushu Inst. of Tech. (Japan)

12:25-13:40

Lunch

G-7: Advanced Sensing and Connectivity

13:40-14:50 Meeting Room 5

Session Chair: H. Majima (Toshiba Corp.)

T. Minotani (NTT Device Technology Lab.)

13:40 G-7-01 (Invited)

QZSS Short Message Synchronized SS-CDMA Communication

°S. Kameda¹, K. Ohya¹, H. Oguma², N. Suematsu¹, ¹Tohoku Univ. (Japan), ²National Inst. of Tech., Toyama College (Japan)

14:10 G-7-02

High Volume Testing and Calibration Technique of CMOS Analog Circuits for System-on-Chips and Microprocessors

°T. Oshita¹, J. Douglas¹, A. Krishnamoorthy¹, ¹Intel Corp. (USA)

Friday, September 22

14:30 G-7-03

A Temperature Monitor Circuit with Small Voltage Sensitivity using a Topology Reconfigurable Ring Oscillator

°T. Kishimoto¹, T. Ishihara¹, H. Onodera¹, ¹Kyoto Univ. (Japan)

14:50-15:10

Coffee Break

G-8: Advanced MEMS Sensors and Analog Front End

15:10-16:20 Meeting Room 5

Session Chair: K. Johguchi (Shinshu Univ.)
J. C. Guo (NCTU)

15:10 G-8-01 (Invited)

Open Innovation of CMOS-MEMS Integrated Devices by Open Facility

°Y. Mita¹, ¹Univ. of Tokyo (Japan)

15:40 G-8-02

A Capacitive Sensor Circuit Based on Relaxation Oscillator for Sub-1mG MEMS Inertial Sensors

°M. Takayasu¹, S. Doshō¹, H. Ito¹, D. Yamane¹, T. Konishi^{1,2}, K. Machida¹, N. Ishihara¹, K. Masu¹, ¹Tokyo Tech (Japan), ²NTT Adv. Tech. Corp. (Japan)

16:00 G-8-03

A 120dBΩ 16MHz Pseudo Differential CMOS Analog Front End Circuit for Optical Probe Current Sensor

°T. Uekura¹, K. Oyanagi, M. Sonehara¹, T. Sato¹, K. Miyaji¹, ¹Shinshu Univ. (Japan)

02: Interconnect Technologies, MEMS, and Reliability

H-5: TSV & 3D Integration

9:30-11:00 Meeting Room 6

Session Chair: M. Mariappan (Tohoku Univ.)
S. Ogawa (AIST)

9:30 H-5-01 (Invited)

Advanced Packaging Technology to Address Micro-bump

Friday, September 22

Solder Bonding and Warpage in Large-die 3D IC using
22nm ULK Dielectrics

°K. Sakuma¹, J. Knickerbocker¹, ¹IBM T. J. Watson
Research Center (USA)

10:00 H-5-02

Evaluation of Substrate Noise Suppression Method to
Mitigate Crosstalk among TSVs

°Y. Araga¹, K. Kikuchi¹, M. Aoyagi¹, ¹AIST (Japan)

10:20 H-5-03

The large-area backside etching method by changing
backside layout using loading effect and ARDE for
foundry-based fabrication

°Y. Okamoto¹, Y. Tohyama¹, N. Usami¹, Y. Mita¹, ¹Univ. of
Tokyo (Japan)

10:40 H-5-04

Characterization of Cu-TSVs Fabricated by a New All-Wet
Process

°M. Xiong^{1,2}, Y. Yan², Y. Ding², H. Kino¹, T. Fukushima¹, T.
Tanaka¹, ¹Tohoku Univ. (Japan), ²Beijing Inst. of Tech.
(China)

11:00-11:15

Coffee Break

Joint Session (Area 2&7)

H-6: Optical Interconnects and Sensors

11:15-12:30 Meeting Room 6

Session Chair: M. Fujino (Univ. of Tokyo)

F. Boeuf (STMicroelectronics)

11:15 H-6-01 (Invited)

Heterogeneous Integration Based on Low-Temperature
Bonding for Advanced Optoelectronic Devices

°E. Higurashi^{1,2}, ¹AIST (Japan), ²Univ. of Tokyo (Japan)

11:45 H-6-02

Membrane-based GaInAs/InP waveguide-type p-i-n
photodetector fabricated on Si substrate using
Benzocyclobutene bonding

Friday, September 22

^oZ. Gu¹, T. Uryu¹, D. Inoue¹, T. Amemiya¹, N. Nishiyama¹,
S. Arai¹, ¹Tokyo Tech (Japan)

12:00 H-6-03

Fabrication of VTPC-TG Pixels for 3D Structure CMOS
Image Sensor Applications

S.-K. Park¹, ^oD. Woo¹, M.-K. Na¹, P.-S. Kwag¹, H.-R. Lee¹,
K.-W. Ro¹, K.-H. Kim¹, D.-K. Lee¹, C. Hong¹, I.-W. Cho¹,
J.-H. Park², K.-D. Yoo², ¹SK Hynix (Korea), ²Hanyang
Univ. (Korea)

12:15 H-6-04 (Late News)

Influence of different plasma treatments on low-
temperature Au-Au bonding and its application to hermetic
packaging

^oM. Yamamoto¹, E. Higurashi^{1,2}, T. Suga¹, R. Sawada³, T.
Itoh¹, ¹Univ. of Tokyo (Japan), ²AIST (Japan), ³Kyushu
Univ. (Japan)

12:30-13:40

Lunch

07: Photonic Devices and Related Technologies

H-7: Silicon Photonics II

13:40-14:55 Meeting Room 6

Session Chair: T. Shimizu (PETRA)

T. Amano (AIST)

13:40 H-7-01 (Invited)

High power Silicon laser based on the dressed photon
technology

^oT. Kawazoe¹, ¹Tokyo Denki Univ. (Japan)

14:10 H-7-02

1.7 μm Wavelength Tunable Laser Diode Using Silicon
External Cavity

^oS. Takei¹, T. Kita¹, H. Yamada¹, ¹Tohoku Univ. (Japan)

14:25 H-7-03

Demonstration of Distributed Feedback Silicon Evanescent
Quantum Dot Laser

^oB. Jang¹, T. Tsuchizawa^{2,3}, H. Nishi^{2,3}, T. Nakamura³, S.

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Iwamoto¹, Y. Arakawa¹, ¹Univ. of Tokyo (Japan), ²NTT Device Tech. Labs. (Japan), ³Photonics Electronics Tech. Res. Association (Japan)

14:40 H-7-04 (Late News)

Silicon on Insulator Nanowire Photodiode with Nanoscale Bow-Tie Surface Plasmon Antenna for Light Detection Applications

°Y. Sharma¹, H. Satoh¹, H. Inokawa¹, ¹Shizuoka Univ. (Japan)

14:55-15:10 Coffee Break

H-8: Silicon Photonics III

15:10-16:25 Meeting Room 6

Session Chair: S. Saito (Univ. of Southampton)

K. Ohira (Toshiba Corp.)

15:10 H-8-01

High Speed and Low Power Consumption Silicon Thermo-optical Phase Shifter

°Y. Chiba¹, T. Kita¹, H. Yamada¹, ¹Tohoku Univ. (Japan)

15:25 H-8-02

Performance Benchmarking of InGaAsP, Si_{0.8}Ge_{0.2} and Si-based Photonics Homojunction and Heterojunction PN Modulators

°F. Boeuf^{1,2}, N. Sekine², S. Takagi², M. Takenaka², ¹STMicroelectronics (France), ²Univ. of Tokyo (Japan)

15:40 H-8-03

Mid-Infrared Si-photonic Devices Based on 340 nm SOI Platform

°H. Wang¹, ¹Nanyang Technological Univ. (Singapore)

15:55 H-8-04 (Invited)

Line Beam Scanner using Slow-Light Waveguides in Si Photonics

°T. Baba¹, K. Kondo², ¹Yokohama National Univ. (Japan), ²Tokyo Tech (Japan)

13: Applications of Nanotubes, Nanowires, and Graphene and related 2D materials

J-5: Advanced Functional Nanowire Devices

9:30-10:45 Meeting Room 7

Session Chair: M. Arita (Univ. of Tokyo)

S. Hara (Hokkaido Univ.)

9:30 J-5-01 (Invited)

Flexible Optoelectronic Devices Based on Nitride Nanowires Embedded in Polymer Films

°M. Tchernycheva¹, N. Guan¹, X. Dai¹, H. Zhang¹, V. Piazza¹, A. Kapoor^{2,3}, C. Bougerol^{2,4}, L. Mancini¹, F. H. Julien¹, L. Lu¹, M. Morassi¹, N. Gogneau¹, J. -C. Harmand¹, L. Largeau¹, M. Foldyna⁵, J. Eymery^{2,3}, C. Durand^{2,3}, ¹CNRS, Univ. Paris Saclay (France), ²Univ. Grenoble Alpes (France), ³CEA-CNRS “Nanophysique et Semiconducteurs” group, CEA-INAC-PHELIQS (France), ⁴CEA-CNRS “Nanophysique et Semiconducteurs” group, CNRS, Institut Néel (France), ⁵LPICM-CNRS, Ecole Polytechnique (France)

10:00 J-5-02

Efficient Coupling of Lateral Force in GaN Nanorod Piezoelectric Nanogenerators by Vertically Integrated Pyramided Si Substrate

°C. -L. Wu¹, S. -J. Tsai¹, C. -Y. Lin¹, C. -L. Wang¹, J. -W. Chen¹, C. -H. Chen², ¹National Cheng Kung Univ. (Taiwan), ²National Synchrotron Radiation Research Center (Taiwan)

10:15 J-5-03

Highly Stable Heavily-Doped Oxide Contacts on Oxide Nanowires: Reliable Low Contact Resistance and Enhancement of Long-term Sensor Response

H. Zeng¹, °T. Takahashi¹, K. Nagashima¹, T. Yanagida¹, ¹Kyushu Univ. (Japan)

10:30 J-5-04

Al-catalyzed Silicon Nanowire Formation and its Application for Photovoltaic Device

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°W. Jevasuwan¹, T. Subramani¹, C. Junyi¹, K. C. Pradel¹, T. Takei¹, N. Fukata¹, ¹NIMS (Japan)

10:45-11:15 **Coffee Break**

J-6: Characterization & Properties of Nanowires

11:15-12:30 Meeting Room 7

Session Chair: K. Kawaguchi (Fujitsu Labs. Ltd.)
S. Hara (Hokkaido Univ.)

11:15 J-6-01 (Invited)

Synchrotron-based Characterization of Nanowires and Nanowire Devices

°A. Mikkelsen¹, ¹Lund Univ. (Sweden)

11:45 J-6-02

Analysis of Bending Mechanism in MnAs/InAs Heterojunction Nanowires

°T. Kadowaki¹, R. Kodaira¹, S. Hara¹, ¹Hokkaido Univ. (Japan)

12:00 J-6-03

Enhancement of Thermoelectric Performance of p-type Short Silicon Nanowires

°Y. Himeda¹, S. Hashimoto¹, S. Ohba¹, R. Yamato¹, T. Matsukawa², T. Watanabe¹, ¹Waseda Univ. (Japan), ²AIST (Japan)

12:15 J-6-04 (Late News)

InAs Nanotube FETs with Atomic-Layer-Deposited Al₂O₃/ZnO Gate-Stack

°S. Sasaki¹, K. Tateno¹, G. Zhang¹, ¹NTT Basic Res. Labs. (Japan)

12:30-13:40 **Lunch**

02: Interconnect Technologies, MEMS, and Reliability

J-7: Latest Research for Interconnect Technologies, MEMS, and Reliability

13:40-14:40 Meeting Room 7

Session Chair: M. Fujino (Univ. of Tokyo)

S. Ogawa (AIST)

13:40 J-7-01 (Late News)

New Characterization Technique for Detection of Atomic-sized Crystalline Defects and Strain Using Moiré Method

°M. Kodera¹, Q. Wang², S. Ri², H. Tsuda², A. Yoshioka¹, T. Sugiyama¹, T. Hamamoto¹, N. Miyashita¹, ¹Toshiba Electronic Devices & Storage Corp. (Japan), ²AIST (Japan)

13:55 J-7-02 (Late News)

Enlarging the Nanocylinder Size for Through-Si-Via Applications

°M. Mariappan¹, T. Fukushima¹, K. Mori¹, J. Bea¹, H. Hashimoto¹, M. Koyanagi¹, ¹Tohoku Univ. (Japan)

14:10 J-7-03 (Late News)

Al-foil-based low-loss coplanar waveguides directly bonded to sapphire substrates

°K. Matsuura¹, J. Liang¹, K. Maezawa², N. Shigekawa¹, ¹Osaka City Univ. (Japan), ²Univ. of Toyama (Japan)

14:25 J-7-04 (Late News)

A Tri-axis MEMS Accelerometer with a Gold Electroplated Single-proof-mass and Segmented Electrodes

°S. Otake¹, D. Yamane¹, T. Konishi^{1,2}, T. Saito², H. Ito¹, S. Doshō¹, N. Ishihara¹, K. Machida¹, K. Masu¹, ¹Tokyo Tech (Japan), ²NTT Advanced Tech. Corp. (Japan)

01: Advanced LSI Processing & Materials Science

K-5: Ferroelectric Material

9:30-10:55 Meeting Room 8

Session Chair: K. Kakushima (Tokyo Tech)

O. Nakatsuka (Nagoya Univ.)

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9:30 K-5-01 (Invited)

CMOS Compatible Ferroelectric Devices for Beyond 1X nm Technology Nodes

°S. Müller¹, ¹Ferroelectric Memory GmbH (Germany)

10:00 K-5-02

Polarization Switching Behavior of HfO₂-based Ferroelectric Ultrathin Films Studied through Coercive Field Characteristics

°S. Migita¹, H. Ota¹, H. Yamada¹, K. Shibuya¹, A. Sawa¹, A. Toriumi², ¹AIST (Japan), ²Univ. of Tokyo (Japan)

10:20 K-5-03

Thickness-dependent ferroelectric phase evolution in doped HfO₂

°L. Xu¹, T. Nishimura¹, S. Shibayama¹, T. Yajima¹, S. Migita², A. Toriumi¹, ¹Univ. of Tokyo (Japan), ²AIST (Japan)

10:40 K-5-04 (Late News)

Direct Evidence of 3-nm-thick Ferroelectric HfO₂

°X. Tian¹, S. Shibayama¹, T. Nishimura¹, T. Yajima¹, S. Migita², A. Toriumi¹, ¹Univ. of Tokyo (Japan), ²AIST (Japan)

10:55-11:15 Coffee Break

K-6: Theory and Modeling

11:15-12:15 Meeting Room 8

Session Chair: T. Nakayama (Chiba Univ.)

H. Arimura (IMEC)

11:15 K-6-01

Acceleration of Metal-atom Diffusion under Electric Field at Metal/Insulator Interfaces; First-principles Study

°R. Nagasawa¹, Y. Asayama¹, T. Nakayama¹, ¹Chiba Univ. (Japan)

11:35 K-6-02

Guiding principles for the fabrication of V-MOSFETs based on a Si emission model

°T. Nagura¹, K. Chokawa¹, H. Shirakawa¹, M. Araidai^{1,4}, H.

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Kageshima^{2,4}, T. Endoh^{3,4}, K. Shiraishi^{1,4}, ¹Nagoya Univ. (Japan), ²Shimane Univ. (Japan), ³Tohoku Univ. (Japan), ⁴JST-ACCEL (Japan)

11:55 K-6-03

Development of Interatomic Potential of $\text{Ge}_{(1-x-y)}\text{Si}_x\text{Sn}_y$
Ternary Alloy Semiconductors for Classical Lattice
Dynamics Simulation

^oM. Tomita^{1,2}, T. Watanabe¹, ¹Waseda Univ. (Japan), ²JSPS Res. Fellow PD (Japan)

12:15-13:40

Lunch

12: Spintronics Materials and Devices

K-7: Magnetic Tunnel Junctions

13:40-14:55 Meeting Room 8

Session Chair: T. Fukumura (Tohoku Univ.)
S. Ohya (Univ. of Tokyo)

13:40 K-7-01

Magnetic phase transition induced tunneling anisotropic
magnetoresistance in FeRh-based junctions

^oC. Song¹, X. Chen¹, F. Pan¹, ¹Tsinghua Univ. (China)

13:55 K-7-02

Epitaxy and Magneto-Transport Properties in Fully
Epitaxial Fe/GaO_x/Fe Magnetic Tunnel Junctions

^oS. K. Narayananellore¹, N. Doko^{1,2}, N. Matsuo^{1,2}, H. Saito¹, S. Yuasa¹, ¹AIST (Japan), ²Chiba Inst. of Tech. (Japan)

14:10 K-7-03

Evaluation of energy barrier of CoFeB/MgO magnetic
tunnel junctions with perpendicular easy axis using
retention time measurement

E. C. I. Enobio¹, ^oH. Sato¹, S. Fukami¹, H. Ohno¹, ¹Tohoku Univ. (Japan)

14:25 K-7-04

Magnetic tunnel junctions with poly-crystalline Heusler
alloy films

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^oM. Oogane¹, A. Ono¹, Y. Ando¹, ¹Tohoku Univ. (Japan)

14:40 K-7-05

*L*₁₀-MnGa based magnetic tunnel junction for high magnetic field sensor

X. P. Zhao¹, ^oJ. Lu¹, S. W. Mao¹, J. H. Zhao¹, ¹Chinese Academy of Sciences (China)

14:55-15:10

Coffee Break

K-8: Spintronics Devices

15:10-16:25 Meeting Room 8

Session Chair: C. Song (Tsinghua Univ.)

T. Uemura (Hokkaido Univ.)

15:10 K-8-01

Integration of Interconnected Magnetic Tunnel Junctions for Spin Torque Majority Gates

^oD. Wan¹, M. Manfrini¹, L. Souriau¹, S. Sayan¹, J. Jussot¹, J. Swerts¹, N. Rassoul¹, K. B. Gavan¹, L. Wouters¹, K. Paredis¹, C. Huyghebaert¹, A. Vaysset¹, A. Thiam¹, M. Ercken¹, C. J. Wilson¹, D. Mocuta¹, I. P. Radu¹, ¹IMEC (Belgium)

15:25 K-8-02

Asymmetric behavior of the planar Hall effect of perpendicularly magnetized Co on Pt epitaxial film

^oJ. R. Ryu¹, C. O. Avci², M. Mann², M. Kohda¹, G. Beach², J. Nitta¹, ¹Tohoku Univ. (Japan), ²Massachusetts Inst. of Tech. (USA)

15:40 K-8-03

Current-induced switching in paramagnetic-CoGa buffer / *L*₁₀ MnGa / MgO structure with a perpendicular magnetic anisotropy

^oM. Takikawa¹, K. Suzuki¹, R. Ranjbar¹, S. Mizukami¹, ¹Tohoku Univ. (Japan)

15:55 K-8-04

Ambipolar transport and modulation of electronic properties of Mn₂CoAl films by ionic liquid gating

^oK. Ueda¹, S. Hirose¹, M. Mori¹, H. Asano¹, ¹Nagoya Univ.

(Japan)

16:10 K-8-05 (Late News)

Voltage Controlled Magnetic Anisotropy at $\text{Fe}_{1-x}\text{Co}_x\text{Pd}/\text{MgO}$ Interface

°A. K. Shukla¹, M. Goto¹, K. Nawaoka¹, J. Suwardy¹, S. Miwa¹, Y. Suzuki¹, ¹Osaka Univ. (Japan)

08: Advanced Material Synthesis and Crystal Growth Technology

M-5: Nanostructures: Synthesis and Properties

9:30-10:45 Meeting Room 2

Session Chair: T. Iwai (Fujitsu Labs. Ltd.)

T. Hoshi (NTT Device Tech. Labs.)

9:30 M-5-01 (Invited)

Nanospectroscopic investigation of individual free-standing semiconductor nanowires using nanoprobe-cathodoluminescence techniques

°K. Watanabe^{1,2}, ¹Osaka Univ. (Japan), ²NIMS (Japan)

10:00 M-5-02

Improved optical properties of low density InAs/GaAs quantum dots by controlling partial capping process

°M. Kakuda¹, Y. Ota¹, K. Kuruma¹, K. Watanabe¹, S. Iwamoto¹, Y. Arakawa¹, ¹Univ. of Tokyo (Japan)

10:15 M-5-03

MOCVD Selective Growth of InAs Nanowires on Patterned Silicon Substrate by Optimizing Gas Flow Rate and Annealing Temperature

°D. Anandan¹, H. W. Yu¹, H. L. Ko¹, R. K. Kakkerla¹, V. Nagarajan¹, S. K. Singh¹, E. Y. Chang¹, ¹National Chiao Tung Univ. (Taiwan)

10:30 M-5-04

Materials growth and band offset parameters of the $\text{Al}_2\text{O}_3/\text{In}_{0.28}\text{Ga}_{0.72}\text{Sb}/\text{AlSb}/\text{GaSb}/\text{GaAs}$ heterostructure

°S. H. Huynh¹, M. T. H. Ha¹, H. B. Do¹, T. A. Nguyen¹, Y. D. Jin¹, J. W. Lin¹, K. S. Yang¹, C. -C. F. Chang¹, Q. H. Luc¹, E.

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Y. Chang¹, ¹National Chiao Tung Univ. (Taiwan)

Joint Session (Area 6&14)

N-5: Advanced Power Device Technologies I

9:30-10:45 Meeting Room 3

Session Chair: T. Tanaka (Panasonic Corp.)

K. Kobayashi (Toshiba Electronic Devices & Storage Corp.)

9:30 N-5-01 (Invited)

Recent achievements and pending challenges in Gallium Nitride vertical device development

°S. Chowdhury¹, ¹Univ. of California, Davis (USA)

10:00 N-5-02

Suppression of Positive Bias Temperature Instability in GaN-MOSFETs

°Y. Kajiwara¹, T. Yonehara¹, D. Kato¹, H. Saito¹, K. Uesugi¹, A. Shindome¹, M. Kuraguchi¹, A. Yoshioka¹, S. Nunoue¹, ¹Toshiba Corp. (Japan)

10:15 N-5-03

650 Volt GaN Quality and Reliability- Readiness for Automotive Applications

°K. Shono¹, T. Hosoda¹, Y. Asai¹, R. Barr², K. Smith², Y. Wu², P. Parikh², ¹Transphorm Japan, Inc. (Japan), ²Transphorm, Inc. (USA)

10:30 N-5-04

Investigations on Electrical Characteristics of 1-kV pnp SiC BJTs Compared with npn SiC BJT

°T. Okuda¹, T. Kimoto¹, J. Suda^{1,2}, ¹Kyoto Univ. (Japan), ²Nagoya Univ. (Japan)

10:45-11:15

Coffee Break

N-6: Advanced Power Device Technologies II

11:15-12:30 Meeting Room 3

Session Chair: K. Tsuda (Toshiba Infrastructure Systems & Solutions Corp.)

D. Hisamoto (Hitachi, Ltd.)

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11:15 N-6-01 (Invited)

Demonstration of Reduction in V_{ce} (sat) of IGBT based on a 3D Scaling Principle

°K. Kakushima¹, T. Hoshii¹, K. Tsutsui¹, A. Nakajima², S. Nishizawa³, H. Wakabayashi¹, I. Muneta¹, K. Sato⁴, T. Matsudai⁵, W. Saito⁵, T. Saraya⁶, K. Itou⁶, M. Fukui⁶, S. Suzuki⁶, M. Kobayashi⁶, T. Takakura⁶, T. Hiramoto⁶, A. Ogura⁷, Y. Numasawa⁷, I. Omura⁸, H. Ohashi¹, H. Iwai¹,
¹Tokyo Tech (Japan), ²AIST (Japan), ³Kyushu Univ. (Japan), ⁴Mitsubishi Electric Corp. (Japan), ⁵Toshiba Electronic Devices & Storage Corp. (Japan), ⁶Univ. of Tokyo (Japan), ⁷Meiji Univ. (Japan), ⁸Kyushu Inst. of Tech. (Japan)

11:45 N-6-02

5.0 kV Breakdown-Voltage Vertical GaN p-n Junction Diodes

°H. Ohta¹, K. Hayashi¹, F. Horikiri², T. Nakamura¹, T. Mishima¹,
¹Hosei Univ. (Japan), ²Sciocs Company Ltd. (Japan)

12:00 N-6-03

Potential of the 0.35 μ m CMOS gate driver technology for the GaN power devices

°S. Miyano¹, T. Akagi¹, S. Abe¹, S. Matsumoto¹,
¹Kyushu Inst. of Tech. (Japan)

12:15 N-6-04

Vertical-type 2DHG Diamond MOSFETs

°N. Oi¹, T. Kudo¹, T. Muta¹, S. Okubo¹, I. Tsuyuzaki¹, T. Kageura¹, M. Inaba^{1,2}, S. Onoda³, A. Hiraiwa¹, H. Kawarada¹,
¹Waseda Univ. (Japan), ²Nagoya Univ. (Japan), ³National Inst for Quantum and Radiological Sci. and Tech. (Japan)

12:30-13:40

Lunch

06: Compound Semiconductor Electron Devices & Related Technologies

N-7: Compound Semiconductor Device & Process

13:40-14:55 Meeting Room 3

Session Chair: A. Wakejima (Nagoya Inst. of Tech.)

T. Suzuki (JAIST)

13:40 N-7-01

Removal of reactive-ion-etching damage from n-GaN surface using a photoelectrochemical process

°S. Matsumoto¹, M. Toguchi¹, T. Sato¹, ¹Hokkaido Univ. (Japan)

13:55 N-7-02

High Thermal Stability of Abrupt SiO₂/GaN Interface with Low Interface State Density

°T. X. Nguyen^{1,2}, N. Taoka², A. Ohta¹, K. Makihara¹, H. Yamada², T. Takahashi², M. Ikeda¹, M. Shimizu², S. Miyazaki¹, ¹Nagoya Univ. (Japan), ²AIST-NU GaN Advance Device Open Innovation Lab. (Japan)

14:10 N-7-03

High-performance E-mode recessed GaN Power MIS-HEMT with La-silicate gate insulator

°C. C. Hsu¹, J. H. Lee¹, Y. C. Lin¹, J. C. Lin¹, C. H. Wu¹, J. N. Yao¹, H. T. Hsu¹, K. Kakushima², H. Iwai², E. Y. Chang¹, ¹National Chiao Yung Univ. (Taiwan), ²Tokyo Tech (Japan)

14:25 N-7-04 (Late News)

Cryogenic DC and RF Characteristics of InGaAs/InAs/InGaAs Channel HEMTs

°A. Endoh¹, I. Watanabe¹, A. Kasamatsu¹, T. Mimura^{1,2}, ¹NICT (Japan), ²Fujitsu Labs. Ltd. (Japan)

14:40 N-7-05 (Late News)

Enhancing the Performance of Ni-In_{0.53}Ga_{0.47}As MOSFETs Using Post Silicon Dopant Process

°H. Q. Luc¹, W. J. Lin¹, S. K. Yang¹, C. C. Chang¹, C. -C. C. Fan¹, B. H. Do¹, M. T. H. Ha¹, H. S. Huynh¹, D. Y. Jin¹, A. T. Nguyen¹, C. Y. Lin¹, E. Y. Chang¹, ¹National Chiao Tung Univ. (Taiwan)